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LIST OF PATENTS AND PUBLICATIONS  
FOR APPLICANTS INFORMATION  
DISCLOSURE STATEMENT

(USE SEVERAL SHEETS IF NECESSARY)

APPLICANT: Eldridge, et al.

FILING DATE: 06/13/2001

GROUP: 2839

Reference Designation

U.S. Patents

Examiner Initial	Document Number	Date	Name	Class	Filing Date Subclass if appropriate
<i>EP</i>	AA 5,513,430	5/7/96	Yanof et al.	29/846	
<i>EP</i>	AB 5,632,631	5/27/97	Fjelstad et al.	439/82	
<i>EP</i>	AC 5,829,128	11/3/98	Eldridge et al.	29/855	
<i>EP</i>	AD 5,974,662	11/2/99	Eldridge et al.	29/842	11/9/95
<i>EP</i>	AE 6,064,213	5/16/00	Khandros et al.	324/754	1/15/97
<i>EP</i>	AF 6,184,053	2/6/01	Eldridge et al.	438/52	5/6/97
<i>EP</i>	AG 5,534,784	7/9/96	Lum et al.	324/757	
<i>EP</i>	AH 5,555,422	9/10/96	Nakano	324/754	
<i>EP</i>	AI 5,576,630	9/19/96	Fujita	324/760	
<i>EP</i>	AJ 5,701,085	10/23/97	Malladi et al.	324/754	
<i>EP</i>	AK 5,821,763	10/13/98	Beaman et al.	324/754	
<i>EP</i>	AL 5,944,537	8/31/99	Smith et al.	439/81	

## FOREIGN PATENT DOCUMENTS

Document Number	Date	Country	Class	Filing Date Subclass if appropriate
<i>EP</i> AM WO 91/12706	8/22/91	PCT/US91/01027		
<i>EP</i> AN 0 632 281 A2	1/4/95	EPO 94304359.6		
<i>EP</i> AO WO 98/21597	5/22/98	PCT/NL97/00616		
<i>EP</i> AP				
<i>EP</i> AQ				

## OTHER ART (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

<i>EP</i> AR Novitsky et al.	<u>Formfactor Introduces an Integrated Process for Wafer-Level Packaging, Burn-in Test, and Module Level Assembly</u>	IEEE/IMAPS Int'l March 1999
<i>EP</i> AS Khandros et al.	<u>New Methods for Reducing Costs in Semiconductor Back-End</u>	Semicon Japan 1998
<i>EP</i> AT Formfactor, Inc./Teradyne Inc. White Paper www.formfactor.com	<u>A New Wafer Probe Interface Technology Unsing Compliant Microsprings</u>	1/30/1998

EXAMINER

EVAN PERT *EP*

DATE CONSIDERED

5-15-03

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.